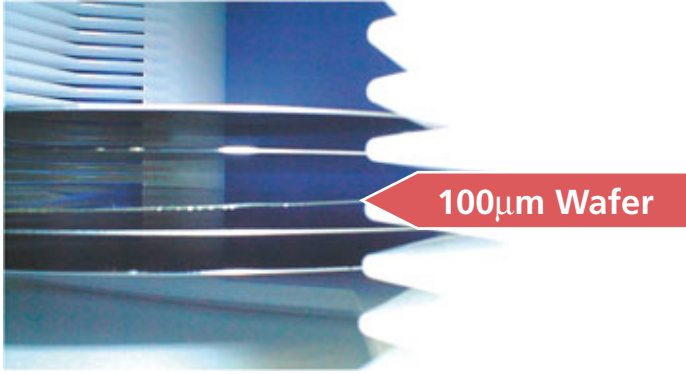


Ultra Thin Wafer

1. Wealthy Experience and Many Delivery Records.
2. Auto Transfer of 50 μ m Wafer w/o Wafer Support.
3. Process Capability for Supported Wafer (WSS).
4. ESC for Ultra Thin Wafer w/ and w/o Wafer Support.
5. Commonality Parts in Implanter, Sputter and Etcher

Ultra Thin Wafer

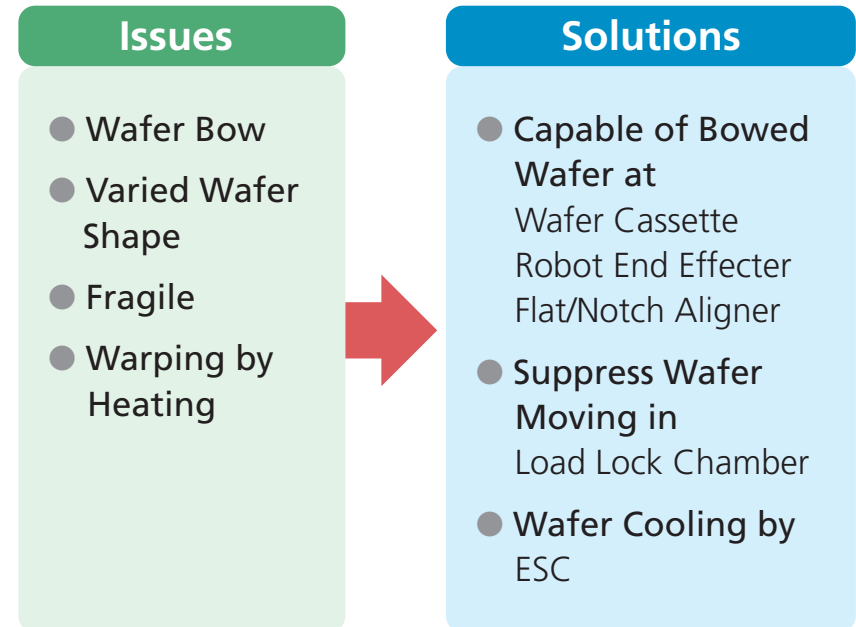
Thickness: 150 μ m~50 μ m
Size: 125mm, 150mm, 200mm



100 μ m Wafer

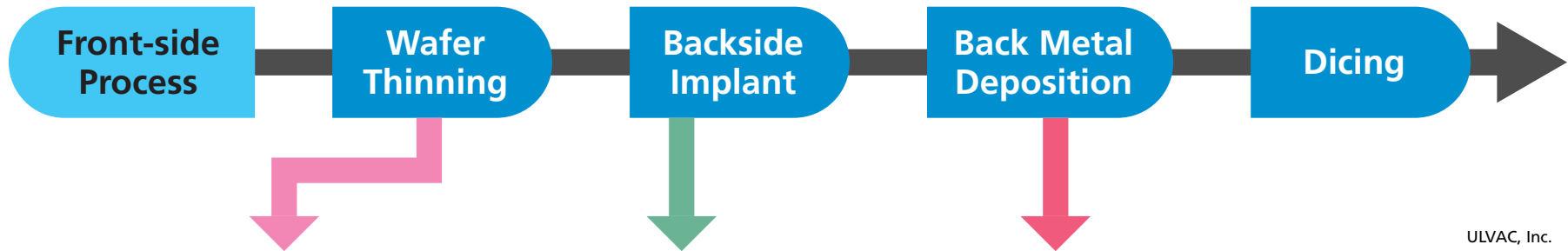
Market

Power Device (IGBT), 3D Stacked Device
Flexible Device



Tape Support	Tape Thickness: 200-300 μ m Applicable Wafer: >100 μ m
Glass Support	Glass Thickness: Various Applicable Wafer: <100 μ m Adhesive Material: Various

Process Flow of power Devices



ULVAC, Inc.



Ion Implanter	Wafer Size: 125mm, 150mm Thickness: 50μm~150μm >15tools
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Sputter(PVD)	Wafer Size: 125mm~200mm Thickness: 50μm~150μm >20tools
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